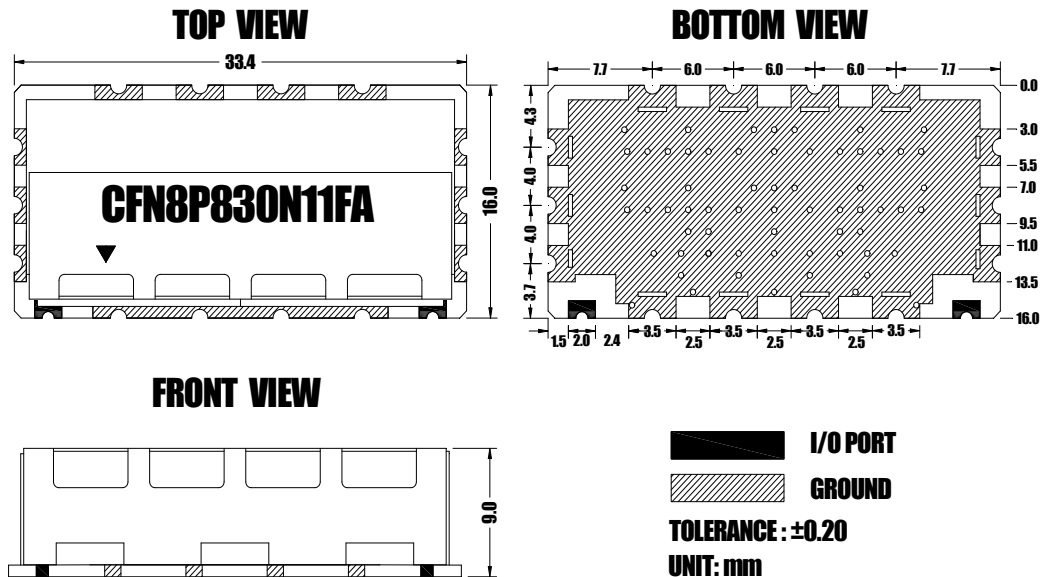


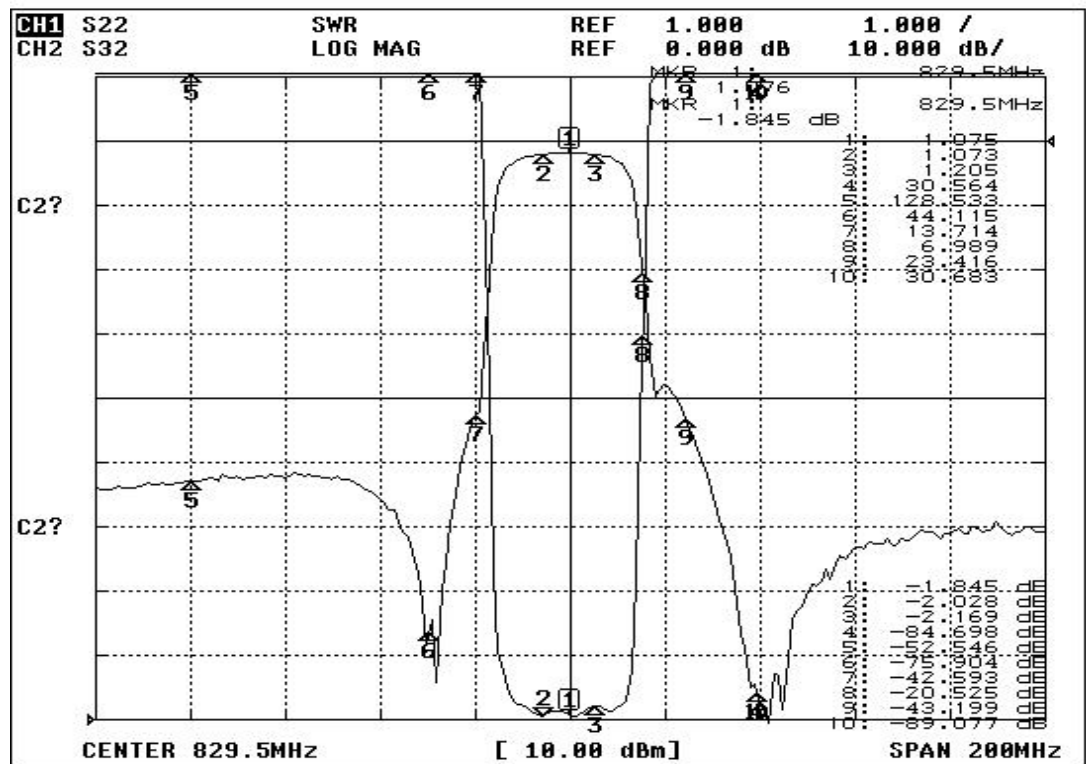
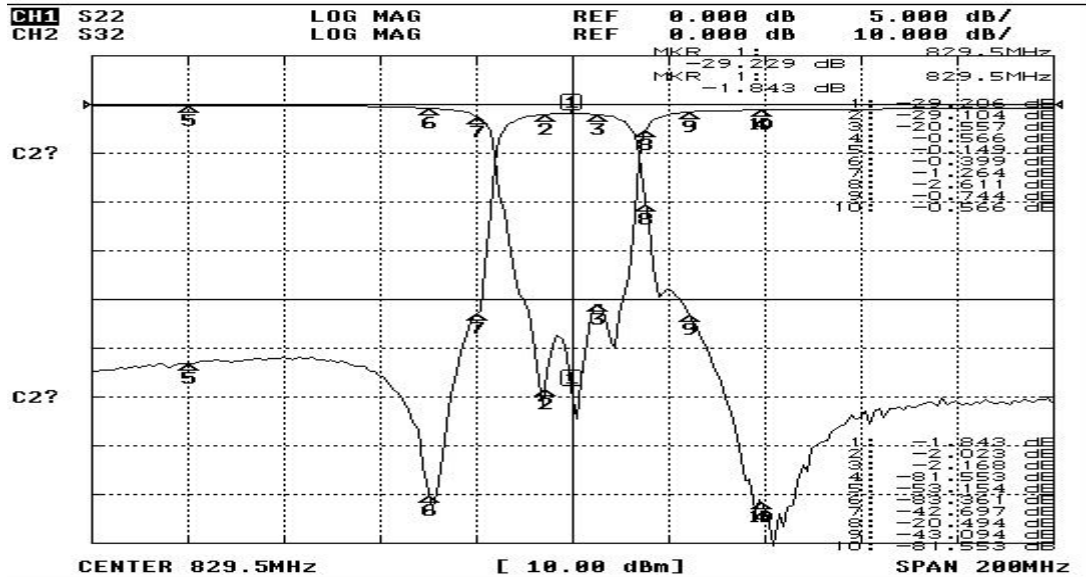
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	829.5	MHz
Bandwidth [BW]	fo ±5.5 [824.0~835.0]	MHz
Insertion Loss in BW	2.3	dB max
Ripple in BW	0.18dB/1MHZ max	dB max
Return Loss in BW	20.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	30.0 dB min @ 1~750	MHz
	58.0 dB min @ 750~800	MHz
	18.0 dB min @ 800~810	MHz
	42.0dB min @ 845~854	MHz
	52.0dB min @ 869~880	MHz
	45.0dB min @ 880~1000	MHz
Group Delay Variation		ns max
Input Power	2	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

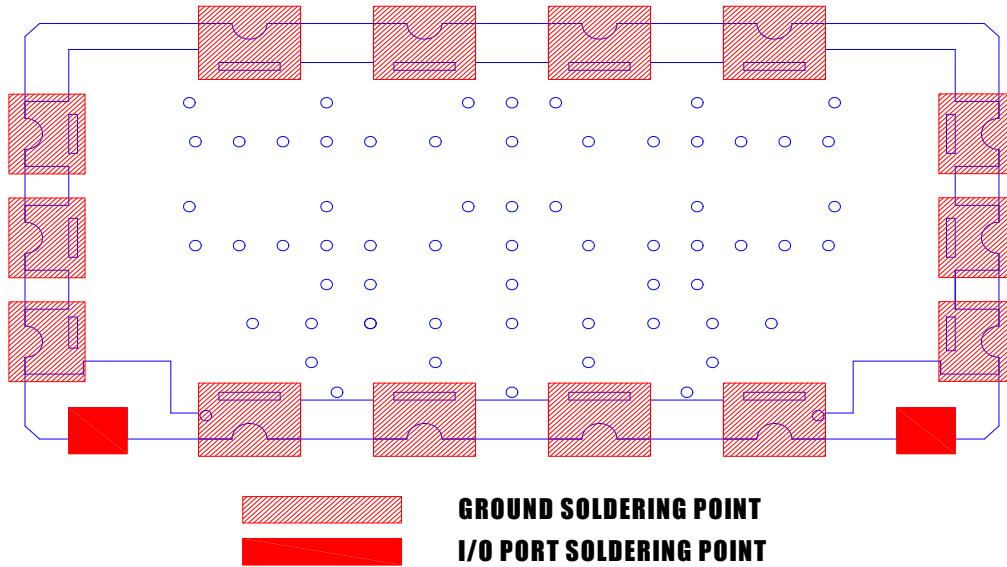
Mechanical Specification



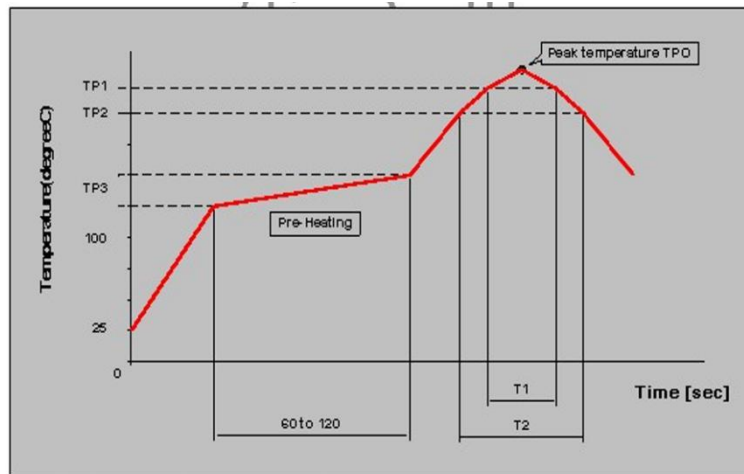
Plot Data



Recommneded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180